

Date 10/11/2005

Qualification Plan # 3526-10-11-2005-445

Group Definition 5

New or Major Change in Assembly Process/Package for a Qualified Device

Device	3526	Mask Rev	DE-M5	Package	N-18	Process	40V	BondWire	Au 1.25
Die Attach	8600	Mold Cmpd:	G600	Pkg Suppl:	(H)	Pretest Pgm:	S1526.FT		
Lead Finish:	Matte Tin (Sn)	Bond Diagram	BD1526/DE-N	Burn-in Ckt:	1526J	Posttest Pgm:	S1526.QA		
Lot Number	1 E521002JA	2 E521002JB	3 E21002JC	4	5	6			
Date Code	1 0539A	2 0540A	3 0541A	4	5	6			

Life Test*Hrs/Cycles*

<i>Qual Num</i>	<i>Lot</i>	<i>Condition</i>	<i>Plan</i>	<i>Actual</i>	<i>Start</i>	<i>End</i>	<i>S/S</i>	<i>Rej Notes:</i>
2005-RM-157	E521002JA	125	1000hrs	1000	11/1/2005	12/19/2005	50	0 Passed

Thermal Shock*Hrs/Cycles*

<i>Qual Num</i>	<i>Lot</i>	<i>Condition</i>	<i>Plan</i>	<i>Actual</i>	<i>Start</i>	<i>End</i>	<i>S/S</i>	<i>Rej Notes:</i>
2005-RM-157	E521002JA	-55C to +125C	100 cycles	100	11/21/2005	11/2/2005	50	0 Passed
2005-RM-158	E521002JB	-55C to +125C	100 cycles	100	11/4/2005	11/8/2005	50	0 Passed
2005-RM-165	E21002JC	-55C to +125C	100 cycles	100	11/4/2005	11/14/2005	48	0 Passed

Temperature Cycle*Hrs/Cycles*

<i>Qual Num</i>	<i>Lot</i>	<i>Condition</i>	<i>Plan</i>	<i>Actual</i>	<i>Start</i>	<i>End</i>	<i>S/S</i>	<i>Rej Notes:</i>
2005-RM-157	E521002JA	-65C to +150C	100 cycles	100	11/1/2005	11/7/2005	50	0 Passed
2005-RM-158	E521002JB	-65C to +150C	100 cycles	100	11/4/2005	11/8/2005	50	0 Passed
2005-RM-165	E21002JC	-65C to +150C	100 cycles	100	11/4/2005	11/7/2005	50	0 Passed

Autoclave*Hrs/Cycles*

<i>Qual Num</i>	<i>Lot</i>	<i>Condition</i>	<i>Plan</i>	<i>Actual</i>	<i>Start</i>	<i>End</i>	<i>S/S</i>	<i>Rej Notes:</i>
2005-RM-157	E521002JA	121C, 15 psig	96 hours	96	11/1/2005	11/15/2005	49	0 Passed
2005-RM-158	E521002JB	121C, 15 psig	96 hours	96	11/4/2005	11/14/2005	50	0 Passed
2005-RM-165	E21002JC	121C, 15 psig	96 hours	96	11/4/2005	12/8/2005	50	0 Passed

Physical Dimensions

<i>Qual Num</i>	<i>Lot</i>	<i>Condition</i>	<i>Start</i>	<i>End</i>	<i>S/S</i>	<i>Rej Notes:</i>
2005-RM-157	E521002JA	SGQ1044	10/14/2005	10/18/2005	3	0 Passed

Marking Permanency

<i>Qual Num</i>	<i>Lot</i>	<i>Condition</i>	<i>Start</i>	<i>End</i>	<i>S/S</i>	<i>Rej Notes</i>
2005-RM-157	E521002JA	SGQ1038	10/14/2005	10/14/2005		Laser marked

Solderability

<i>Qual Num</i>	<i>Lot</i>	<i>Condition</i>	<i>Start</i>	<i>End</i>	<i>S/S</i>	<i>Rej Notes:</i>
2005-RM-157	E521002JA	SGQ1041	10/14/2005	10/18/2005	22	0 Passed
2005-RM-158	E521002JB	SGQ1041	10/14/2005	10/20/2005	22	0 Passed
2005-RM-165	E21002JC	SGQ1041	10/14/2005	10/18/2005	22	0 Passed

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Moisture Sensitivity

<i>Qual Num</i>	<i>Lot</i>	<i>Condition</i>	<i>Start</i>	<i>End</i>	<i>S/S</i>	<i>Rej Notes:</i>
2005-RM-157	E521002JA	JSTD-020B	10/13/2005	11/16/2005	12	0 Passed Pb free MSL level 1
2005-RM-158	E521002JB	JSTD-020B	10/26/2005	11/18/2005	12	0 Passed Pb free MSL level 1

Construction Analysis

<i>Qual Num</i>	<i>Condition</i>	<i>CA Report #</i>	<i>CA By</i>	<i>Start</i>	<i>End</i>	<i>S/S</i>	<i>Rej Notes:</i>
2005-RM-157	SGQ1343	37746	Photometrics	10/14/2005	10/24/2005		Approved by Michelle Hazard

Supporting Data:

SG3526_Hana_18Ld_PDIP_PbFree (Construction Analysis Report)

Comments:

Pb-free Qualification of Hana

Signatures:

Responsible Engineer

Responsible Engineering Manager

Reliability Manager